

#### 40V 175°C DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>C</sub> = +25°C (Note 9)
40V	$8.6 m\Omega @ V_{GS} = 10 V$	45A

# Description and Applications

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

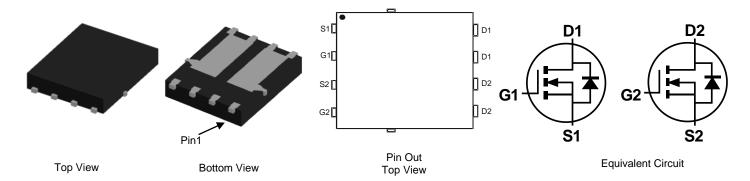
- Backlighting
- Power Management Functions
- DC-DC Converters

## **Features and Benefits**

- Rated to +175°C Ideal for High Ambient Temperature Environments
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: PowerDI5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)



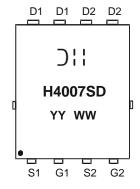
# **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMTH4007SPD-13	PowerDI5060-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



⊃¦¦ = Manufacturer's Marking
 H4007SD = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 14 = 2014)
 WW = Week (01 - 53)



# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V <sub>DSS</sub>	40	V		
Gate-Source Voltage	V <sub>GSS</sub>	±20	V		
Continuous Drain Current (Note 6)	T <sub>C</sub> = +25°C (Note 9)	I <sub>D</sub>	45	А	
	$T_{C} = +100^{\circ}C$		38.1		
Continuous Drain Current (Note 5)	$T_A = +25$ °C $T_A = +70$ °C	I <sub>D</sub>	14.2 11.9	А	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	90	Α		
Maximum Continuous Body Diode Forward Current (Note 6)	Is	34	Α		
Avalanche Current, L = 0.1mH		I <sub>AS</sub>	20	Α	
Avalanche Energy, L = 0.1mH	E <sub>AS</sub>	89	mJ		

#### **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$P_D$	2.6	W	
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	57	°C/W	
Total Power Dissipation (Note 6)	$P_D$	37.5	W	
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta JC}$	4	°C/W	
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +175	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	40	_	_	V	$V_{GS} = 0V$ , $I_D = 1mA$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μΑ	V <sub>DS</sub> = 32V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	$V_{GS(th)}$	2	_	4	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	7.5	8.6	mΩ	$V_{GS} = 10V, I_D = 17A$	
Diode Forward Voltage	$V_{SD}$	_	0.85	_	V	$V_{GS} = 0V, I_{S} = 17A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C <sub>iss</sub>	_	2,026	_	pF	V 20V V 0V	
Output Capacitance	Coss	_	702	_	pF	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	84.8	_	pF		
Gate Resistance	Rg	_	0.46	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge	Qg	_	41.9	_	nC		
Gate-Source Charge	$Q_{gs}$	_	10	_	nC	$V_{DS} = 30V, I_{D} = 20A, V_{GS} = 10V$	
Gate-Drain Charge	$Q_{gd}$	_	11.5	_	nC	1	
Turn-On Delay Time	t <sub>D(on)</sub>	_	7	_	ns		
Turn-On Rise Time	t <sub>r</sub>	_	11.5	_	ns	$V_{DD} = 30V, V_{GS} = 10V,$	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	15.6	_	ns	$I_D = 20A$ , $R_G = 3\Omega$	
Turn-Off Fall Time	t <sub>f</sub>	_	8.8	_	ns		
Body Diode Reverse Recovery Time	t <sub>rr</sub>	_	29.9	_	nS	-I <sub>F</sub> = 20A, di/dt = 100A/μs	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	_	23		nC		

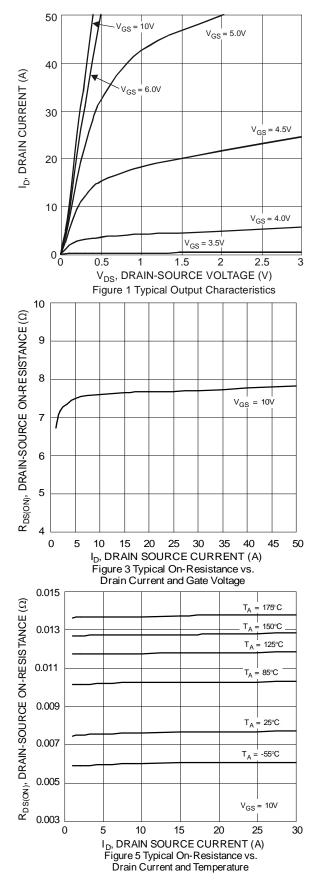
5. Device mounted on FR-4 substrate PC board, 2oz. copper, with thermal bias to bottom layer 1inch square copper plate.

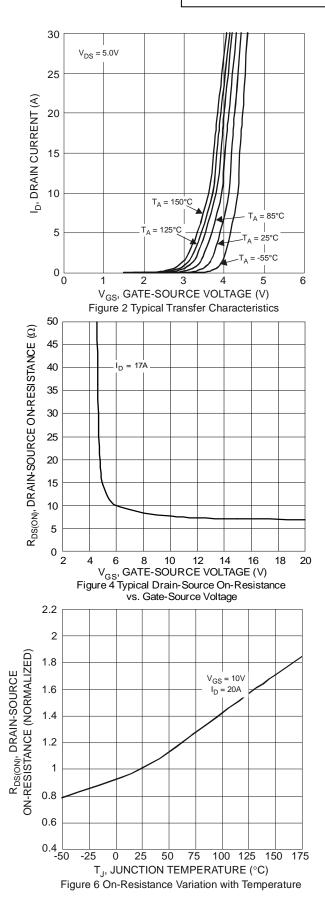
6. Thermal resistance from junction to soldering point (on the exposed drain pad).

7. Short duration pulse test used to minimize self-heating effect.

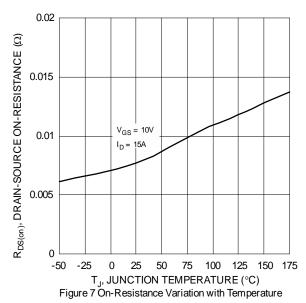
Guaranteed by design. Not subject to product testing.
 Package limited.

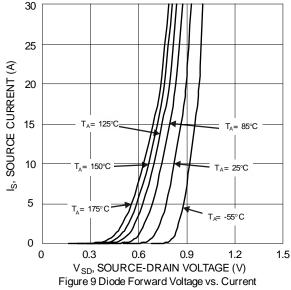


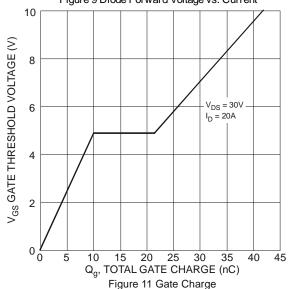












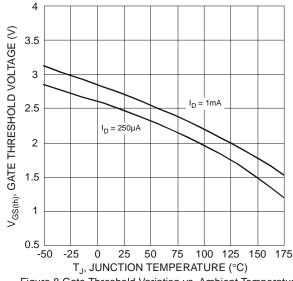
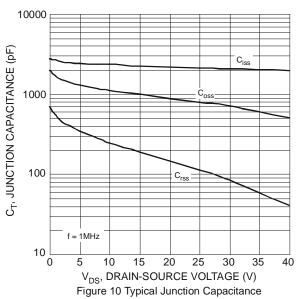
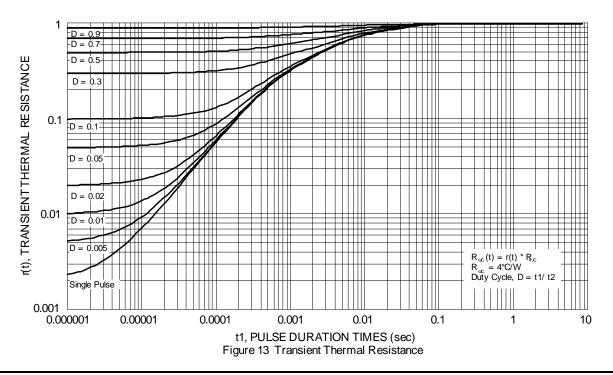


Figure 8 Gate Threshold Variation vs. Ambient Temperature



100
| R<sub>DS(on)</sub> | P<sub>W</sub> = 10µs | P<sub>W</sub> = 10µs | P<sub>W</sub> = 10µs | P<sub>W</sub> = 100µs | P<sub>W</sub> = 10µs | P<sub>W</sub>

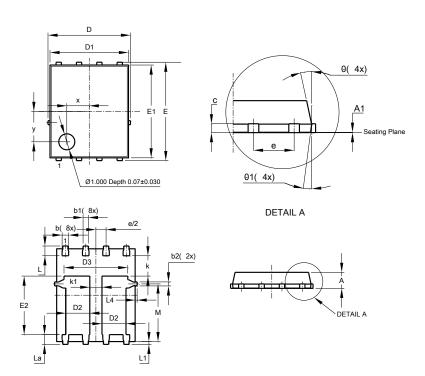




## **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

#### PowerDI5060-8 (Type C)

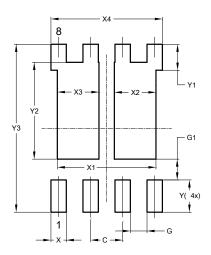


PowerDI5060-8 (Type C)					
Dim	Min Max		Тур		
Α	0.90	1.10	1.00		
A1	0	0.05	0.02		
b	0.33	0.51	0.41		
b1	0.300	0.366	0.333		
b2	0.20	0.35	0.25		
С	0.23	0.33	0.277		
D	5	.15 BS0	2		
D1	4.85	4.95	4.90		
D2	1.40	1.60	1.50		
D3	-	-	3.98		
Е	6	.15 BS0	2		
E1	5.75	5.85	5.80		
E2	3.56	3.76	3.66		
е	1	.27BS0			
k	-	-	1.27		
k1	0.56	-	-		
L	0.51	0.71	0.61		
La	0.51	0.71	0.61		
L1	0.05	0.20	0.175		
L4	-	-	0.125		
М	3.50	3.71	3.605		
Х	1	-	1.400		
у	•	-	1.900		
θ	10°	12°	11°		
θ1	6°	8°	7°		
All Dimensions in mm					



Suggested Pad Layout
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

#### PowerDI5060-8 (Type C)



Dimensions	Value (in mm)		
С	1.270		
G	0.660		
G1	0.820		
X	0.610		
X1	3.910		
X2	1.650		
Х3	1.650		
X4	4.420		
Y	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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